

EV Group Advances Leadership in Optical Lithography with Next-Generation EVG150 Resist Processing Platform – November 9, 2022

semiconductor
packaging news

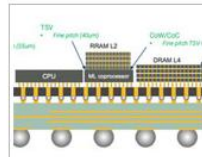
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November 9, 2022

Legacy Tools, New Tricks: Optical 3D Inspection

Stacking chips is making it far more difficult to find existing and latent defects, and to check for things like die shift, leftover particles from other processes, co-planarity of bumps, and adhesion of different materials such as dielectrics. There are several main problems: Not everything is visible from a single angle, particularly when vertical structures are used; Various structures ...



IMAPS Device Packaging Conference

The esteemed 19th DPC 2023 brings together industry engineers, researchers and top experts participating in a multi-faceted technical program and unique networking events. March 13-16. **IMAPS**



Micro Dispensing Technology White Paper

The trend toward micro-dispensing technology increases as electronic assembly's shrink & component packages decrease in size. **DL Technology**



The Semiconductor Market Roller Coaster Ride is Back

Pat Gelsing attended the WSJ Tech event in late October and as always had some interesting things to say about the state of the semiconductor industry. In the interview ... **3DInCites**

Dispositioning Hermetic Microelectronic Components With High Internal Moisture

This white paper presents four options for dispositioning hermetic electronic components non-compliant on internal water vapor content. **Technical Paper**

Nvidia making new chip to suit US curbs on China

Nvidia Corp, the most valuable chipmaker in the US, has begun producing a processor for China that conforms to new rules aimed at limiting that country's access to ... **Taipei Times**

Technical Papers

- Mobile Antennas and Power Devices that Break the Mold
- Atmospheric Oxygen-only Plasma for Decapsulation of Advanced Packages
- Effects of Long-Term Storage on Mechanical and Electrical Integrity
- The Great Debate: Ball Bonding vs Wedge Bonding
- Chip-Last HDFO Interposer-PoP
- Air Gap, Buried Layer and Micro-Channel Measurement
- Essential Practices for Gold Mitigation of Electronic Components

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Need Tin Mitigation Services?

Watch a video showing precision robotic component tinning. Fully programmable robotic hot solder dip machines control dip depth, dwell times & temps to meet GEIA-0006 standards. **Circuit Technology Center**



Today's Sponsor



Test Your Knowledge

Where was the first parking meter installed? See answer below.

Flip Chip Bonding / C4 technology

High precision process of assembly and connection technology (AVT) for contacting unmounted semiconductor chips by means of balls - so-called "bumps". **Tresky Automation**



Press Releases

Indium Expert to Present on Innovative Metal 3D Additive Manufacturing Technology at TCT Conf.

Indium Corporation's David Socha, technology assessment manager, will present on Indium Corporation's innovative 3D-EZ-Release™ build plate, a cutting-edge technology that ... **Indium Corporation**

EV Group Advances Leadership in Optical Lithography with Next-Generation EVG150 Resist Processing Platform

EV Group (EVG) announced that it has strengthened its portfolio of optical lithography solutions with the unveiling of the next-generation 200-mm version of its EVG@150 automated ...

EV Group

SEMICON Europa 2022 Keynotes to Highlight Chip Industry Growth Opportunities and Advanced Technologies

SEMICON Europa 2022 will gather microelectronics experts and visionaries 15-18 November in Munich, Germany for insights into advanced technologies that are driving ... **SEMI**

MRS™ Sensor for Challenging Measurement & Inspection

Chip sector must boost renewables deployment

Recent discussions about Taiwan Semiconductor Manufacturing Co (TSMC) have focused on a potential 1-nanometer fab in Taoyuan's Longtan District and the global chip ...

Taipei Times

TSMC approves US\$5.71-billion capital budget

The Taiwan Semiconductor Manufacturing Co. (TSMC) board of directors met and approved a capital budget of US\$5.71 billion, with the vast majority to be spent on ...

Focus Taiwan

Tech war: China to host world forum on semiconductors in the shadow of Covid-19 controls, latest US hi-tech export restrictions

China will kick off a major international semiconductor forum next week, as Beijing seeks to project stability in the nation's chip supply chain amid the latest hi-tech export ...

South China Morning Post

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Next Steps For Improving Yield

Chipmakers are ramping new tools and methodologies to achieve sufficient yield faster, despite smaller device dimensions, a growing number of systematic defects, immense ...

Semiconductor Engineering

SK hynix Leading the Way in the HKMG Revolution

As performance requirements for DRAM increase due to limitations in traditional scaling technology systems, HKMG has emerged as a breakthrough solution. By using ...

EE Times

Samsung Electronics begins mass production of 8th-Gen Vertical NAND

Samsung Electronics announced on Nov 7 at Flash Memory Summit 2022 and Samsung Memory Tech Day 2022 that it has begun mass producing a 1-terabit (Tb) triple ...

Digitimes

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China's second-largest chip maker after SMIC gets green light for US\$2.5 billion Shanghai IPO

Hong Kong-listed Hua Hong Semiconductor, China's second-largest chip maker, has received regulatory approval for a US\$2.5 billion initial public offering (IPO) ...

South China Morning Post

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CyberOptics Corporation

Quote of the Day

Men are born to succeed, not to fail.

Henry David Thoreau

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Welco® AP5112 Type 7 paste enables the single-step printing process for both flip-chip & passive component attach, which significantly reduces assembly cost and solder defects.

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What Year Was It?

Nazis Launch Kristallnacht

In an event that would foreshadow the Holocaust, German Nazis launch a campaign of terror against Jewish people and their homes and businesses.

The day was Nov 9. What year was it?



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Heterogeneous advanced semiconductor packages like SiP are quickly outpacing traditional inspection technologies. Learn how to master advanced package inspection.

Koh Young America, Inc.



Cartoon of the Day



"I'm married to my career. I keep a photo of my desk on my desk."

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How to Wire Pull?

Calendar

- [Nov 15, 2022: SEMICON Europa 2022](#)
- [Nov 17, 2022: Overview of semiconductor manufacturing webinar for American attendees](#)
- [Nov 18, 2022: Compound Semiconductor Materials Technology Seminar](#)
- [Dec 14, 2022: SEMICON Japan 2022](#)

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Learn how to perform an optimal pull test on wires or ribbons. This extensive guide also covers loop height measurement, vector pull, and SMD gull-wing leads pull. Download now. **xyztec**



Test Your Knowledge Answer

Where was the first parking meter installed?

Answer: Oklahoma City, Oklahoma in 1935

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